Final Product Change Notification | 201908007F01

Issue Date: 06-Sep-2019
Effective Date: 04-Dec-2019
Dear *Emma Tempest*,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.
For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

Change Category

[ ] Wafer Fab Process	[X] Assembly Process	[ ] Product Marking	[ ] Test Location	[ ] Design
[ ] Wafer Fab Materials	[ ] Assembly Materials	[ ] Mechanical Specification	[ ]Test Process	[ ] Errata
[ ] Wafer Fab Location	[ ] Assembly Location	[ ] Packing/Shipping/Labeling	[ ] Test Equipment	[ ] Electrical spec./Test coverage
[ ] Firmware	[ ] Other			

NXP-ATKL TEPBGA 27*27 Package Substrate Singulation Method Change From Mechanical Punch To Saw

Description of Change

NXP Semiconductors announces the change of substrate singulation method from mechanical punch to saw for the TEPBGA 27*27 package assembled in NXP-ATKL, Kuala Lumpur, Malaysia assembly facility. For more information about the substrate singulation method change, please refer to the "Communication Package" file attached.

The above change coincides with DeQuMa ID: SEM-PA-14 and SEM-EQ-01.

Reason for Change

The substrate singulation method change is required for customer supply assurance.

Identification of Affected Products

Product part number and marking identification does not change.
A visual comparison between substrate singulation using mechanical punch and saw is provided in the

"Communication Package" file attached.

Product Availability

Sample Information
Samples are available upon request
Sample part numbers information is available in the "Communication Package" file attached.
Production
Planned first shipment 20-Dec-2019

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.
Disposition of Old Products
Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file
Self qualification: view online
Additional documents: view online

Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by 06-Oct-2019.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Nuha Mohd. Adzhar
Position Product Engineer
e-mail address nuha.mohdadzhar@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.
Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands